

IN THE SPECIFICATION

Please amend paragraph 0022 as follows.

[0022] ~~FIG. 12 is a~~ FIGS. 12A and 12B are cross-sectional view views of a alternative semiconductor package packages formed according to an embodiment of the invention.

Please amend paragraph 0066 as follows.

[0066] Leadframes 130 and 140 of FIGS. 4A and 5, respectively, may be provided in packages similar to package 1400 of FIG. 12. In a package 1410 made with leadframe 140, as shown in FIG. 12A, the semiconductor chip 1402 is mounted on inner end segments 200a, 202a in a flip chip style using solder balls 1412.